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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16791**Generic Copy

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**Issue Date:** 22-Mar-2012**TITLE:** ON Semiconductor Seremban added as a second manufacturing Site for CAT6243**PROPOSED FIRST SHIP DATE:** 22-Jun-2012 or earlier upon customer's approval**AFFECTED CHANGE CATEGORY(S):** CAT6243**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Thruston Awalt <[thruston.awalt@onsemi.com](mailto:thruston.awalt@onsemi.com)>**SAMPLES:** Contact your local ON Semiconductor Sales Office**ADDITIONAL RELIABILITY DATA:** Not applicable**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.**DESCRIPTION AND PURPOSE:**

This Process Change Notice is to inform customers that ON Semiconductor is adding ON Semiconductor Seremban as a second manufacturing location for product CAT6243.

The devices listed on this FPCN have historically been assembled &amp; tested at the STARs located in Thailand.

Due to flooding in Thailand, the STARs assembly/test site in Thailand is temporarily out of operation. Moving forward, these devices will be processed at either of the location based on the situation.

There will be no change in device functionality. Reliability will continue to meet or exceed ON Semiconductor's highest standards.



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### RELIABILITY DATA SUMMARY:

Device	NUS3116MT ENG	Wafer Fab	Aizu / ISMF		
Case Outline #	-	Assembly Site	Sbn	Seremban Malaysia	
Package	<b>WDFN8 3X3X0.75mm</b>	Final Test Site	Sbn	Seremban Malaysia	
Mold	G760	Reliability Lab	Sbn	Seremban Malaysia	
Die Attach	CRM1084P	Max. Current		Max.	
Technology	Discrete	Rel Tracking #	S01516A	S01516B	S01516C
Die Size	1.385 X 1.075 mm 1.725 X 1.125 mm	Substrate/ Flag Size	1.975x1.270 mm		

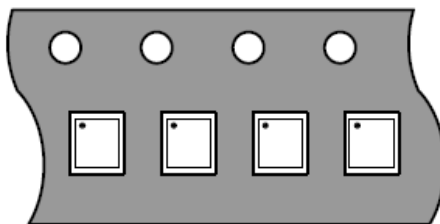
**QUALIFICATION RESULTS AND ANALYSIS:** See attached Qualification Report

**ELECTRICAL CHARACTERISTIC SUMMARY:** No changes in device functionality. Device parameters will continue to meet all data sheet specifications.

**CHANGED PART IDENTIFICATION:** N/A

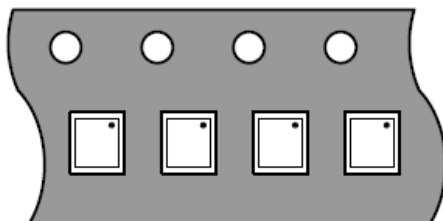
**CHANGED PART ORIENTATION – Tape and Reel packaging:** Applies to all assembly sites used.

**Old orientation:**



Pin 1 (Upper Left)

**New orientation:**



Pin 1 (Upper Right)

### List of affected General Parts:

CAT6243-ADJMT5T3